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Attorney Docket No.: MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
Serial No. : 10/050,507
Confirmation No. : 7687
Filing Date : January 16, 2002
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
Group Art Unit : 2812

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

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37 CFR 1.8(a)

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INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97/98

Sir:

In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. §1.56, listed on the attached Form PTO-1449 are those patents and other publications known to Applicant which may be considered material to the patentability of the claims of the above-identified application.

Applicant respectfully requests that the Examiner consider the documents listed on the attached Form PTO-1449, that these references be made of record in the present application, and that an initialed copy of the attached Form PTO-1449 be returned to the undersigned in accordance with MPEP 609.

Respectfully submitted,

Kristine M. Strodthoff

Kristine M. Strodthoff, Reg. No. 34259

Dated: September 9, 2004

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| U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT | ATTY. DOCKET NO. | Serial No. |
| | MTI-31607 | 10/050,507 |
| | Applicant | Confirmation No. |
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FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

| Examiner Initial | | Document Number | Publication Date | Country | Int'l Class | Sub-Class | Translation (Yes/No) |
|------------------|----|-----------------|------------------|---------|-------------|-----------|----------------------|
| | A1 | 2000-183082 | 06-30-00 | JP | H01L | 21/566 | Abstract |
| | A2 | 2001077294 | 03-23-01 | JP | H01L | 25/065 | Yes |
| | A3 | 99/65282 | 12-16-99 | WO | H05K | 1/11 | N/A |

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

| Examiner Initial | | Non-Patent Document |
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| | B1 | Copy of Australian Patent Office, Search Report, 30 May 2003, 4 pages. |
| | B2 | Al-sarawi, S. et al., "A Review of 3-D Packaging Technology," <i>Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging</i> , Vol 21, Issue 1, Feb. 1998, pp. 2-14. |
| | B3 | Andros, F. et al., "TBGA Package Technology," <i>Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging</i> , Vol. 17, Issue 4, Nov. 1994, pp. 564-568. |
| | B4 | Clot, Ph. et al., "Flip-Chip on Flex for 3D Packaging," 1999. 24 th IEEE/CPMT, 18-19 Oct. 1999, pp. 36-41. |
| | B5 | Ferrando, F. et al., "Industrial Approach of a Flip-Chip Method Using the Stud-Bumps With a Non-Conductive Paste," <i>Adhesive Joining and Coating Technology in Electronics Manufacturing</i> , 2000. Proceedings. 4 th International Conference on, 18-21, June 2000, pp. 205-211. |
| | B6 | Gallagher, C. et al., "A Fully Additive, Polymeric Process for the Fabrication and Assembly of Substrate and Component Level Packaging," <i>The First IEEE International Symposium on Polymeric Electronics Packaging</i> , 26-30, Oct. 1997, pp. 56-63. |
| | B7 | Geissinger, J. et al., "Tape Based CSP Package Supports Fine Pitch Wirebonding," <i>Electronics Manufacturing Technology Symposium</i> , 2002, IEMT 2002, 27 th Annual IEEE/SEMI International, 17-18 July 2002, pp. 41-452. |
| | B8 | Hatanaka, H., "Packaging Processes Using Flip Chip Bonder and Future Directions of Technology Development," <i>Electronics Packaging Technology Conference</i> , 2002. 4 th , 10-12, Dec. 2002, pp. 434-439. |
| | B9 | Haug, R. et al., "Low-Cost Direct Chip Attach: Comparison of SMD Compatible FC Soldering with Anisotropically Conductive Adhesive FC Bonding," <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , Vol. 23, No. 1, Jan 2000, pp. 12-18. |

| Examiner Initials | Date Considered |
|---|-----------------|
| EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | |

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|  <p>U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> | ATTY. DOCKET NO. | Serial No. |
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| Examiner Initial | | Non-Patent Document |
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| | B10 | Isaak, H. et al., "Development of Flex Stackable Carriers" IEEE Electronic Components and Technology Conference, 2000 Proceedings 50th, 5/21/2000-5/24/2000, Las Vegas, NV, USA, pp. 378-84, IEEE Catalog No: 00CH37070. |
| | B11 | Kloeser, J. et al., "Fine Pitch Stencil Printing of Sn/Pb and Lead Free Solders for Flip Chip Technology," <i>IEEE Transactions of CPMT - Part C</i> , vol. 21, No. 1, 1998, pp. 41-49. |
| | B12 | Kheng et al., "Enhancement of Moisture Sensitivity Performance of a FBGA," <i>Proceedings of International Symposium on Electronic Materials & Packaging</i> , 2000, pp. 470-475. |
| | B13 | Li, L. et al., "Stencil Printing Process Development for Flip Chip Interconnect," <i>IEEE Transactions Part C: Electronics Packaging Manufacturing</i> , Vol. 23, Issue 3, July 2000, pp. 165-170. |
| | B14 | Lyons, A. et al., "A New Approach to Using Anisotropically Conductive Adhesives for Flip-Chip Assembly, Part A," <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology</i> , Vol. 19, Issue 1, March 1996, pp. 5-11. |
| | B15 | Teo, Y. et al., "Enhancing Moisture Resistance of PBGA," <i>Electronic Components and Technology Conference</i> , 1998. 48 th IEEE, 25-28 May 1998, pp. 930-935. |
| | B16 | Teutsch, T. et al., "Wafer Level CSP using Low Cost Electroless Redistribution Layer," <i>Electronic Components and Technology Conference</i> , 2000. 2000 Proceedings. 50 th , 21-24 May 2000, pp. Pages: 107-113. |
| | B17 | "The 2003 International Technology Roadmap for Semiconductors: Assembly and Packaging", pp. 1-22 |
| | B18 | Tsui, C. et al. "Pad Distribution Technology for Flip Chip Applications", <i>1998 Electronic Components and Technology Conference</i> , pp. 1098-1102 |
| | B19 | Xiao, G. et al., "Reliability Study and Failure Analysis of Fine Pitch Solder-Bumped Flip Chip on Low-Cost Flexible Substrate Without Using Stiffener," IEEE, 2002. Proceedings 52 nd , 28-31 May 2002, pp. 112-118. |

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